

NOTE: PLEASE CHECK FOR AVAILABILITY, NOT ALL OPTIONS AVAILABLE.

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SPRING OPTION	Y DESCRIPTION (SEE SHEET 5 FOR OPTIONAL VIEWS)	
1	SPRING ON TOP, BOTTOM AND BOTH SIDES	
2	NO SPRINGS	
3	SPRINGS ON TOP AND BOTTOM	
4	SPRINGS ON TOP, BOTTOM AND 1 PER SIDE (STAGGERED)	
5	SAME AS OPTION 4 EXCEPT OPPOSITE STAGGER	

DIM E

PLATING CODE X	PLATING (1)
0	.76uM/30u" G.X.T.
3	.76uM/30u" GOLD
5	1.27uM/50u" GOLD

NOTES:

- 1. HOUSING MATL: HIGH TEMP. THERMOPLASTIC, COLOR BLACK, UL94V-0.
- 2. CONTACT MATL: COPPER ALLOY MATING AREA PLATING: Au C JOVIACI MAIL COFFER ALLOVI MATING AREA PLATING: Au OVER Ni., (SEE TABLE). SOLDER AREA PLATING: 2.54uM/100u" MIN TIN LEAD OVER Ni. LEAD FREE OPTION: SOLDER AREA PLATING: 2.54uM/100u" MIN PURE TIN OVER Ni.
- 3. SHIELDING MAT'L: TIN PLATED COPPER ALLOY.
- 4. ALL DIMENSIONS IN MILLIMETERS AND INCHES.
- (5) SEE SHEET 5 FOR GROUND TAB CONFIGURATION.
- (6) CENTER PEG FOR 8 PORT ONLY.
- (7) COMPANY LOGO LOCATED IN THIS AREA.

PDM: Rev:H

(8) ADD LF SUFFIX AT THE END OF PART NUMBER FOR LEAD FREE OPTION. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 15 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.5mm MINIMUM THICK CIRCUIT BOARD. SEE APLICATION NOTES/PROCEDURES

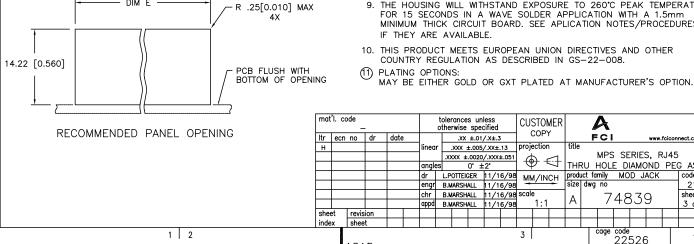
STATUS: Released

213

sheet

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- 10. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008.



ACAD

